CMS Pixel Detector Noise Calibrations Kiriakos Hilbert Northside College Prep Quarknet 2013 Mentored by Dr. Marco Verzocchi





Introduction

- Kiriakos "Kerry" Hilbert
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- 100% Physics Major





Outline

- Large Hadron Collider
- Compact Muon Solenoid Detector
- Pixel Detector

Structure / Layout Readout Electronics Testing Calibration Radiation Damage

LHC: Large Hadron Collider



- Used to study known particles and their interactions
- Looks for new particles and interactions

LHC

- Studies proton-proton collisions
- Peak collisions occur 40 million times per second
- Bunches cross every 25 nanoseconds

Compact Muon Solenoid



- General purpose detector: Higgs, Standard Model, Heavy lons
- 4T solenoidal magnetic field 100,000 times stronger than Earth's magnetic field
- Proton Proton interaction chamber
- 8 Tera Electron Volts

Elements of the CMS



Underground Cavern



Head On View



Side View



CMS Pixel Detector

Pixel Size: 100 x 150 microns Silicon sensors - Ideal Properties Bump-bonded to PSI 46 Read Out Chips (ROCs)

Barrel Pixels

- 3 layers at radii 4.3,
 7.2, and 11 cm
- 48 million pixels
- 11520 ROCs

Forward Pixels

- 4 disks at 34.5 and 46.5 cm from interaction point
- 18 million pixels
- 4320 ROCs

What Happens During a Hit?

- Particle passes through pixel
- If ionizing radiation, electrons knocked loose and "holes" created
- Electron/ "Hole" pairs are proportional to intensity of radiation
- Pulse measured in outer circuit
- Diode Structure -Threshold Voltage



CMS Pixel Detector

 Provides high resolution 3D space point required for track pattern recognition and reconstruction

 1.06 m² area
 66 million channels



Modules of the Pixel Detector



BPIX (Barrel Pixel Detector) has 768 modules





FPIX (Forward Pixel Detector) has 672 modules



Bump Bonding



Small amounts of solder connect the actual sensor to the ROC

Pixel Readout Chip



Barrel Pixel (BPIX)



Forward Pixel (FPIX)



Read Out Electronics Goals

- Register signals produced in sensor
- Store the time, position, and charge of all channels
- Send out the data for bunch crossings as selected by first trigger



• 1.3 million transistors

ROC Circuitry



40 MHz Analog Readout

Reads out:

- Analog Pulse Height
- Pixel Address
 Hit pixel address
 coded in base-6



Analog Readout

- Six discrete analog levels are used to encode hits
- 2 pieces of information correspond to the double column
- 3 pieces of information for the row



Senary Encoding

Senary readout encodes the pixel's address and pulse height in a base 6 numbering system

There was a hit on "row" 425 and column 46

This is the information that the ROC will relay, but what does that mean?

Sum: 159

425 in base 6 is referring to Row 159

Counting in base 6, break down what 425 really means

Each digit corresponds to a component of base 6



Time Stamps and Hits

- Time stamps must be precise
- Correlation between stamps and hits must be completely correlated
- Absolutely crucial

Digitizer and Data Readout

The signal sent through the ROC, at this point, is electrical and analog. It encodes the ROC #, row and column and charge collected of each pixel hit. The electrical signal from the ROC is then converted to an optical signal. This signal makes its way to the FED (Front End Driver) where it is truly digitized and given level thresholds for decoding.

FEDs send digitized data down to the Data Acquisition System (DAQ).

Testing and Calibration Overview

- A large portion of module testing consists of DAC registers programming.
- All of the 26 DACs are set to their default value for each Readout-Chip.
- Running module testing allows individual calibration of crucial DACs.
- Pixel electronic connections and their readouts are tested for functionality.
- Calibration tests are in turn performed, including testing the responses of the noise, trim, and gain of each individual pixel.

Pixel Map



PixelMap_C0

- Basic test performed to see pixel functionality
- "Dead" pixels in the four corners of the sensor
- Most pixels functioning perfectly fine

Baseline Calibration

- Calibrate so that "black" level is in middle of ADC
- Conveys that data will follow "ultra-black" level or signal



Address Level Calibration

 Distinguishes / separates between address levels



S-Curve Calibration

- Checks the efficiency vs. injected charge for sensors
- Response vs. Calibration signal
- Width between plateaus represents the amount of noise present in a pixel



Gain Calibration

ROC0_Col0_Row3



Probing the Pixel Detector

- Instate a voltage from 0 to 600 V on the chip's readout components
- Response curve to ensure that the chip is predictable and reliable
- Should be plateau in the middle of the curve that reflects how efficient the chip is



Impact of Radiation Damage

- Analog current increases with radiation damage
- Slower preamplifier run time
- Higher thresholds for pixels



Conclusion

- CMS's FPIX detector is functioning very efficiently and at an excellent resolution as had been planned
- Its operation takes much calibration to eliminate the effect noise may have
- Programming is an EXTREMELY valuable skill
- Many thanks to my mentor, Dr. Marco Verzocchi, for his endless patience and insightful explanations (I definitely needed them)